

## 1. Description

The IRLML6402TR uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

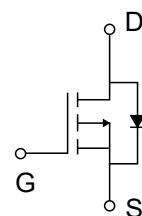
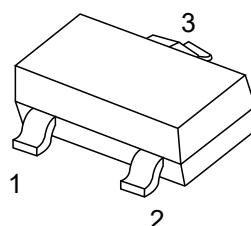
## 2.2 Features

- P-Channel MOSFET
- SOT-23 Footprint
- Available in Tape and Reel
- Low profile(<1.1mm)
- Fast Switching
- Ultra low on-resistance

## 3. Pinning information

Pin	Symbol	Description
1	G	GATE
2	S	SOURCE
3	D	DRAIN

SOT-23



## 4. Maximum ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Units
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	
Continuous Drain Current, $V_{GS}=4.5\text{V}$	$I_D$	-3.7	A
Continuous Drain Current, $V_{GS}=4.5\text{V}$		-2.2	
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	-30	
Power Dissipation	$P_D$	1.3	W
Power Dissipation		0.8	
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	11	mJ



Thermal Resistance.Junction- to-Ambient	$R_{thJA}$	100	$^{\circ}\text{C}/\text{W}$
Lineara Derating Factor		0.01	$\text{W}/^{\circ}\text{C}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Junction and Storage Temperature Range	$T_{STG}$	-55 to 150	

## Notes:

- a.Repetitive Rating :Pulse width limited by maximum junction temperature.
- b.Starting  $T_J=25^{\circ}\text{C}$ ,  $L=1.65\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{AS}=-3.7\text{A}$ .



## 5.Electrical Characteristics $T_A=25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$			-1	$\mu\text{A}$
		$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, T_J=70^\circ\text{C}$			-25	
Gate-source leadage	$I_{GSS}$	$V_{GS}=\pm 12\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.4	-0.55	-0.95	V
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	$V_{GS}=-4.5\text{V}, I_D=-3.7\text{A}$		0.05	0.065	$\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-3.1\text{A}$		0.08	0.135	
Forward Transconductance	$g_{FS}$	$V_{DS}=-10\text{V}, I_D=-3.7\text{A}$	6			S
Input Capacitance	$C_{iss}$	$V_{DS}=-10\text{V}$		633		pF
Output Capacitance	$C_{oss}$			145		
Reverse Transfer Capacitance	$C_{rss}$			110		
Total Gate Charge	$Q_g$	$V_{DS}=-10\text{V}$		8	12	nC
Gate Source Charge	$Q_{gs}$			1.2	1.8	
Gate Drain Charge	$Q_{gd}$			2.8	4.2	
Turn-On DelayTime	$t_{D(\text{on})}$	$I_D=-3.7\text{A}$		350		ns
Rise time	$t_r$			48		
Turn-off delay time	$t_{D(\text{off})}$			588		
Fall time	$t_f$			381		
Reverse recovery time	$t_{rr}$	$T_J=25^\circ\text{C}, I_F=-1\text{A}$		29	43	ns
Reverse recovery charge	$Q_{rr}$		$dI/dt=-100\text{A}/\mu\text{s}$ *2	11	17	nC
Continuous source current	$I_s$	MOSFET symbol showing the integral reversep-n junction diode.			-1.3	A
Pulsed source current *1	$I_{SM}$				-22	
Diode forward voltage	$V_{SD}$	$T_J=25^\circ\text{C}, V=0\text{V}, I_s=-1\text{A}$ *2			-1.2	V

\*1 Repetitive rating,pulse width limited by max.junction temperature.

\* 2 Pulse width  $\leq 400\mu\text{s}$ , Duty cycle  $\leq 2\%$ .



## 6.1 Typical Characteristics

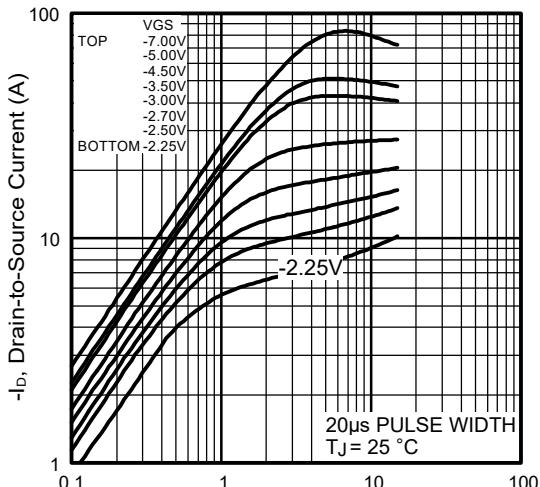
- $V_{DS}$ , Drain-to-Source Voltage (V)

Fig 1. Typical Output Characteristics

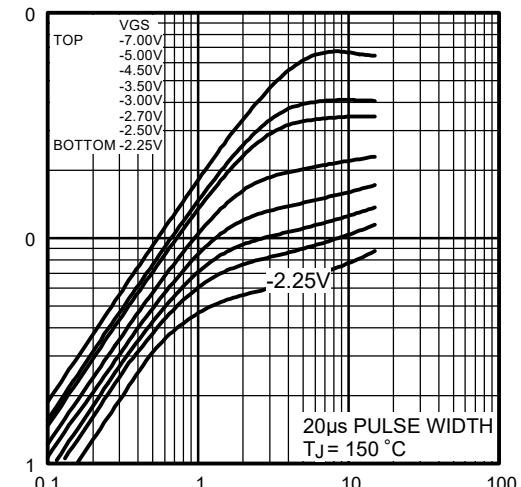
- $V_{DS}$ , Drain-to-Source Voltage (V)

Fig 2. Typical Output Characteristics

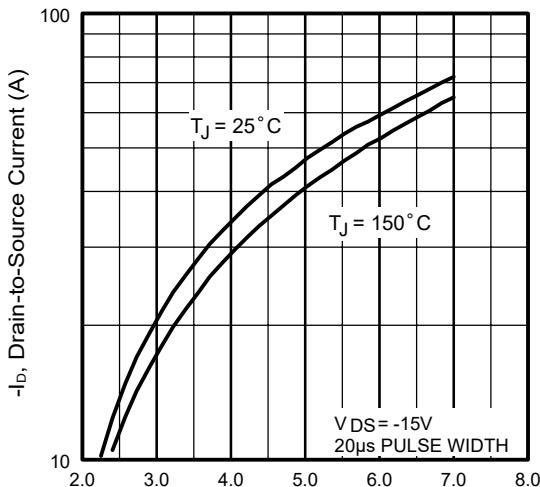
- $V_{GS}$ , Gate-to-Source Voltage (V)

Fig 3. Typical Transfer Characteristics

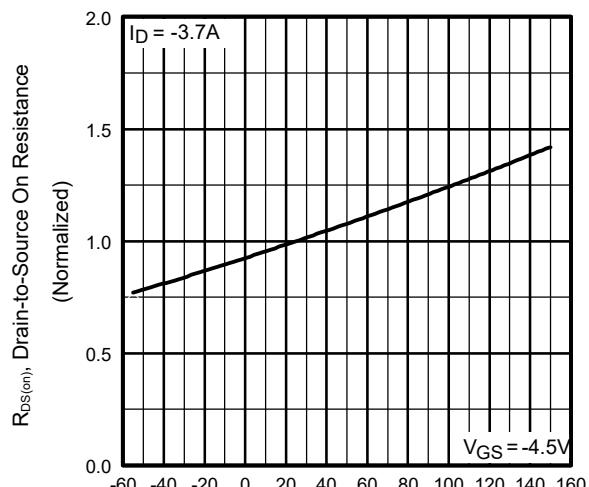
 $T_J$ , Junction Temperature (°C)

Fig 4. Nomalized On-ResistanceVs. Temperature



## 6.2 Typical Characteristics

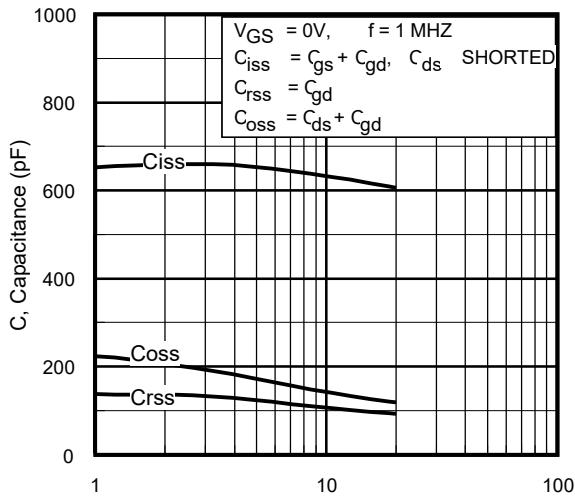


Fig 5. Typical Capacitance Vs.  
Drain-to-Source Voltage

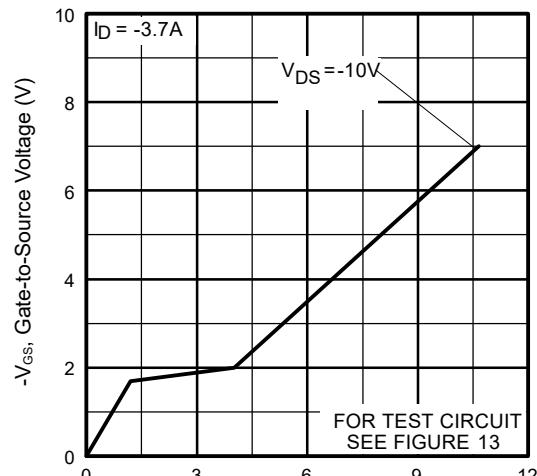


Fig 6. Typical Gate Charge Vs.  
Gate-to-Source Voltage

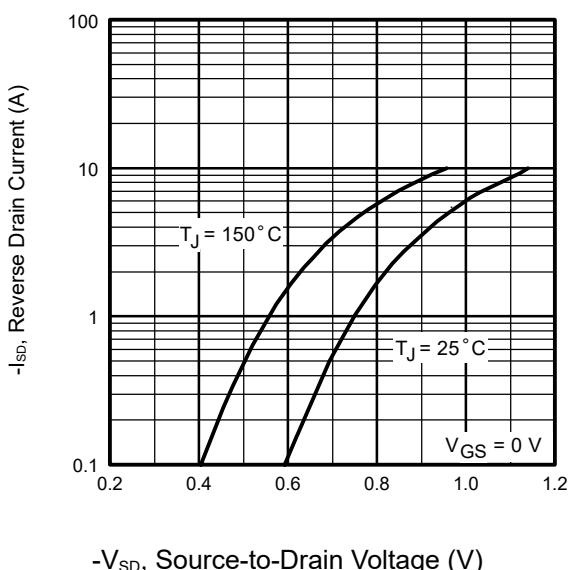


Fig 7. Typical Source-Drain Diode  
Forward Voltage

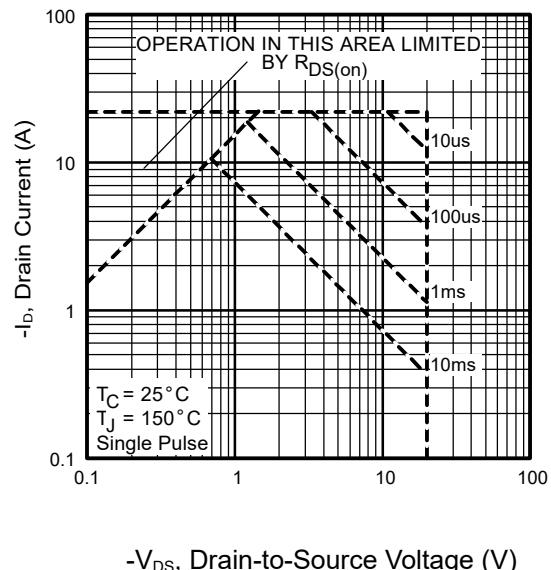


Fig 8. Maximum Safe Operating Area



### 6.3 Typical Characteristics

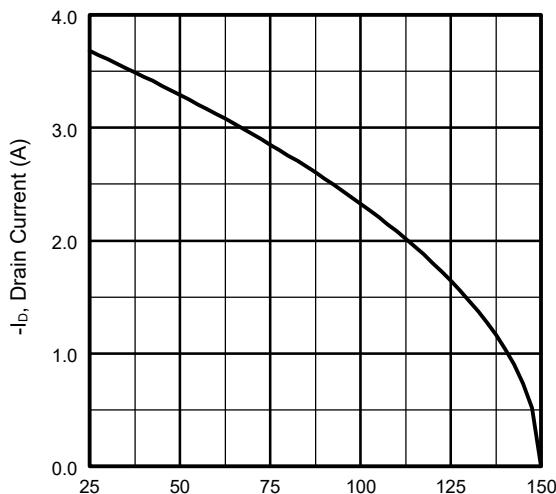
T<sub>C</sub>, Case Temperature (°C)

Fig 9. Maximum Drain Current Vs. Case Temperature

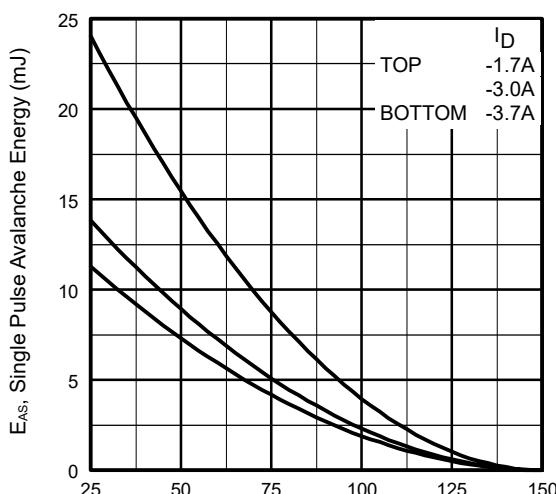
Starting T<sub>J</sub>, Junction Temperature (°C)

Fig 10. Maximum Avalanche Energy Vs. Drain Current

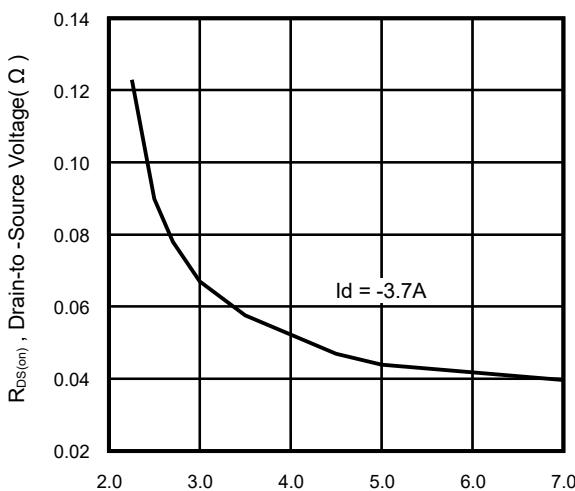
-V<sub>GS</sub>, Gate -to -Source Voltage (V)

Fig 11. Typical On-Resistance Vs. Gate Voltage

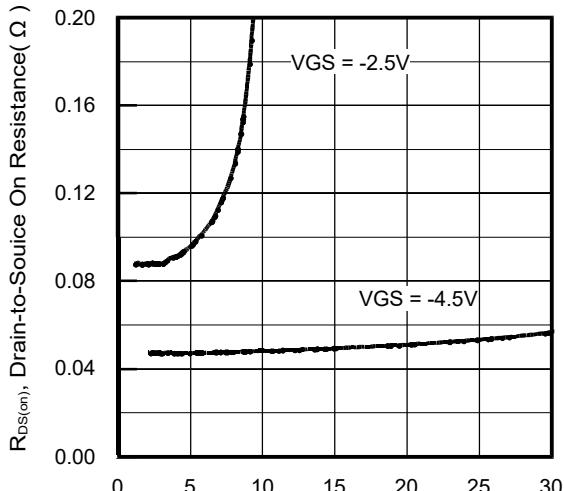
-I<sub>D</sub>, Drain Current (A)

Fig 12. Typical On-Resistance Vs.Drain Current



## 6.4 Typical Characteristics

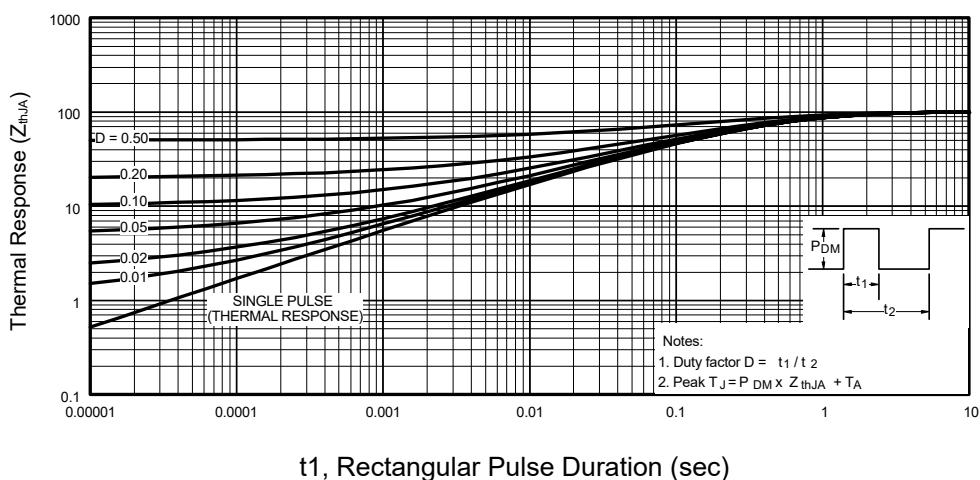
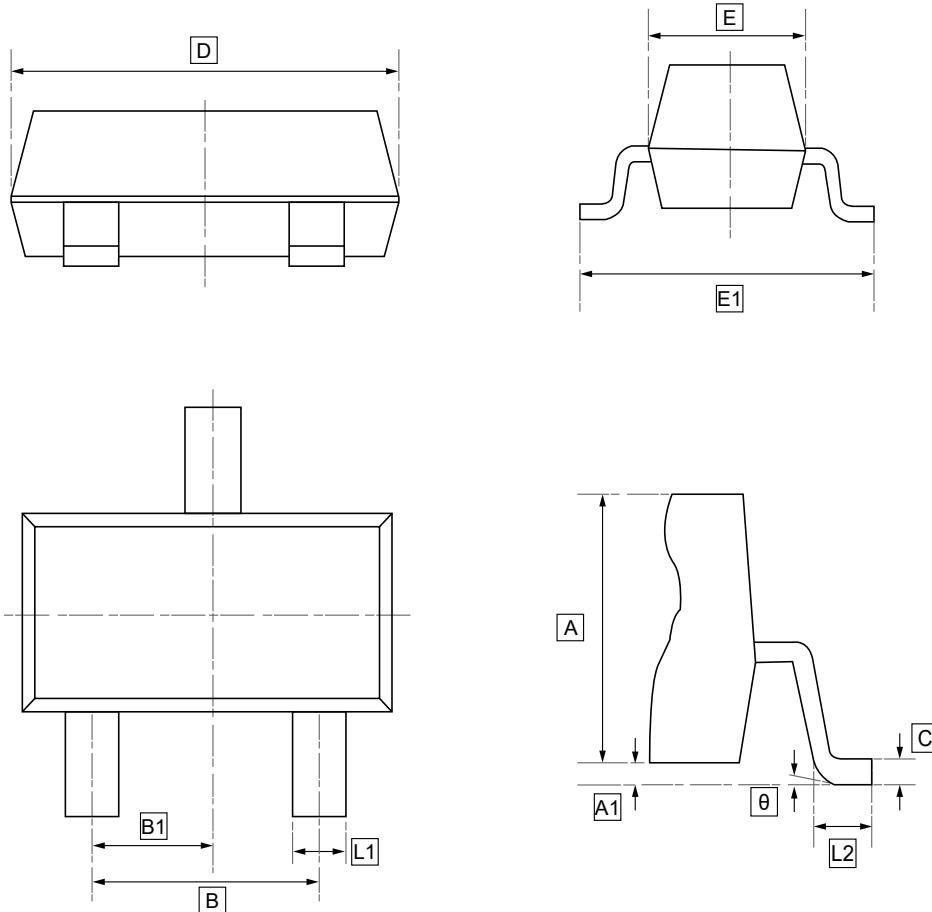


Figure 13. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## 7.SOT-23 Package Outline Dimensions

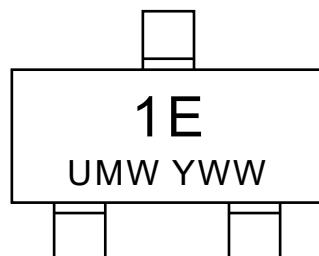


### DIMENSIONS (mm are the original dimensions)

Symbol	A	A1	L1	L2	C	D	E	E1	B	B1	$\theta$
<b>Min</b>	1.050	0.000	0.300	0.350	0.100	2.820	1.500	2.700	1.800	0.950	0°
<b>Max</b>	1.150	0.100	0.500	0.550	0.200	3.020	1.700	2.900	2.000	TYP	8°



## **8.Ordering information**



YWW: Batch Code

Order Code	Package	Base QTY	Delivery Mode
UMW IRLML6402TR	SOT-23	3000	Tape and reel



## **9.Disclaimer**

UMW reserves the right to make changes to all products, specifications. Customers should obtain the latest version of product documentation and verify the completeness and currency of the information before placing an order.

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